



Material Composition Declaration

Package Information

Package	Package Weight (mg)	Terminal Finish	MSL Rating
SOD-523	2	Matte Tin (Sn)	1

Product Group

Type No.	Description
RB751S-40	Diode Schottky 30mA 30V
1SS389	Diode Schottky 100mA 10V
1SS388	Diode Schottky 100mA 40V
BAT54X	Diode Schottky 200mA 30V
RB520S-30	Diode Schottky 200mA 30V
RB521S-30	Diode Schottky 200mA 30V
1SS387	Diode Switching 100mA 80V
1SS400	Diode Switching 100mA 80V
1SS422	Diode Switching 150mA 85V
BAS16X	Diode Switching 200mA 100V
NSD914X	Diode Switching 200mA 100V
BAS516	Diode Switching 250mA 100V
BZX584C2V0 – BZX584C51	Diode Zener 200mW

Component	Material	Substance	CAS No.	Material Mass (%)	Material Mass (mg)	Component Mass (%)	Component Mass (mg)	PPM
Die	Doped Silicon*	Si	7440-21-3	100.00	0.026	1.29	0.026	13000
Wire Bond	Gold	Au	7440-57-5	100.00	0.003	0.13	0.003	1500
Leadframe	Ferrous Alloy	Fe	7439-89-6	56.40	0.386	34.20	0.684	192888
		Ni	7440-02-0	42.00	0.287			143640
		Mn	7439-96-5	0.80	0.005			2736
		Co	7440-48-4	0.50	0.003			1710
		Si	7440-21-3	0.30	0.002			1026
Die Bond	Silver Silicone	Ag	7440-22-4	80.00	0.013	0.81	0.016	6400
		Bisphenol F	28064-14-4	15.00	0.002			1200
		Glycidyl neodeconate	26761-45-5	5.00	0.001			400
Plating	Matte Tin	Sn	7440-31-5	100.00	0.035	1.77	0.035	17500
Encapsulation	EMC	Silica	7631-86-9	79.00	0.976	61.80	1.236	488220
		Epoxy Resin	29690-82-2	20.00	0.247			123600
		Carbon Black	1333-86-4	1.00	0.012			6180

Tolerance ±10%

*Dopant and metallization of the silicon die are not reported in this statement where their concentration is less than the minimum reportable level per EIA JIG-101.

Data disclosed herewith is approximate and is based on information from suppliers surveys, Material Safety Datasheet, engineering calculations and measurements. Won-Top Electronics(WTE) has checked all information carefully and believes it to be correct and accurate. However, WTE cannot assume any responsibility for inaccuracies. WTE reserves the right to change any or all information herein without further notice.

RoHS Declaration

The European Parliament and of the Council on the Restriction of the use of Certain Hazardous Substances in Electrical and Electronics Equipment (RoHS) directive restricts the concentration of Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBD) to 0.1%(1000 PPM) and restricts the concentration of Cadmium (Cd) to 0.01%(100 PPM) in homogeneous materials of electronics products.

The product group listed above and the homogenous materials are compliant with the Directive 2011/65/EU. WTE warrants that all its packing, components and/or products supplied to the Customer and/or its affiliated companies or designated contractors do not contain these hazardous substances in quantity levels higher than or equal to the thresholds to this directive.

Exemptions as declared for the directive are:

7(a) Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead).

7(c)-I Lead in glass (applicable for glass passivated silicon die).